

FINAL PRODUCT/PROCESS CHANGE NOTIFICATION

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13 Sep 2007

SUBJECT: ON Semiconductor Final Product/Process Change Notification #16046

TITLE: Final Notification of Qualification of Nantong-Fujitsu Microelectronics for Assembly/Test of TO-220AB Schottky & Ultrafast Rectifiers.

PROPOSED FIRST SHIP DATE: 13 Dec 2007

AFFECTED CHANGE CATEGORY(S): ON Semiconductor Assembly & Test

AFFECTED PRODUCT DIVISION(S): Automotive & Power Regulation Group

FOR ANY OUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor Sales Office or Mike Schager <mike.schager@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office

ADDITIONAL RELIABILITY DATA: Available

Contact your local ON Semiconductor Sales Office or Laura Riverslaura.rivers@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

DESCRIPTION AND PURPOSE:

This is an FPCN from IPCN 15671 that announced the planned capacity expansion of ON Semiconductor's assembly and test operations of TO-220AB and I2PAK Discrete packaged products, currently built at the PSI Manila facility, to Nantong-Fujitsu's China facility. Upon the expiration of this FPCN, these non-automotive Schottky and Ultrafast TO-220AB devices may be processed at either location. The Nantong-Fujitsu facility is currently used to manufacture ON's DPAK, TO-220AB, and I2PAK devices, and is ISO/TS 16949:2002 certified.

There are minor changes to ON Semiconductor case outline 221A-09, including:

F - Hole Diameter 3.73 max to 4.09 max (in accordance with JEDEC max) J - Lead Thickness 0.46 min to 0.36 min (in accordance with JEDEC min)

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RELIABILITY DATA SUMMARY:

TO-220AB Schottky Rectifier Test Vehicle: MBR60H100CTG

HTSL 150C, 504 hrs 0/240 IOL Ta=25C, delta Tj=100C max, Ton=Toff=3.5 min, 4286 c 0/240 TC Ta=-65/+150C, 500 cycles 0/240 AC/PC 121C, 15psig, 100% RH, 96 hrs 0/240

TO-220AB Ultrafast Rectifier Test Vehicle: MUR1660CTG

TC Ta=-65/+150C, 500 cycles 0/240

ELECTRICAL CHARACTERISTIC SUMMARY:

There are no changes in electrical characteristics; product performance meets data sheet specifications. Characterization data is available upon request.

CHANGED PART IDENTIFICATION:

Product from Nantong-Fujitsu will be identified by NF site code marking

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AFFECTED DEVICE LIST:

MBR40250TG

MBR20200CTG

MBR2535CTLG

MBR41H100CTG

MBR60H100CTG

MBR2030CTLG

MBR4015CTLG

MBR40L45CTG

MBR60L45CTG

MUR620CTG

MUR1610CTG

MUR1615CTG

MUR1620CTG

BYV32-200G

BYW51-200G

MURH840CTG

MURH860CTG

MUR1620CTRG

MUR1640CTG

MUR1660CTG

SUR187SG

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